



512Kx32SRAM PBGA MCP Package Construction
 WEDPS512K32-XBX • WEDPS512K32V-XBX
 Quality and Reliability Report

512K x 32 SRAM PBGA MULTI-CHIP PACKAGE CONSTRUCTION

ENCAPSULANT

- Thickness around die = 0.015 to 0.020 typical
- The encapsulant is not injection molded to control wire sweep effects
- T_G = 150°C
- Moisture sensitivity is to JEDEC level 3

INTERPOSER MATERIAL

- CTE = 12-13 ppm / °C
- Water absorbtion = 0.13%

BALLS

- Eutectic solder Sn63/Pb37
- Diameter = 0.835mm (0.032) Typical

TEST

- Burn-In — 100%-48 hours at 125°C
- Final Electrical Test — 100% at maximum and minimum ambient temperatures

Temperature Ranges Available:

- 55°C to +125°C
- 40°C to +85°C
- 0°C to +70°C

SHIPPING

- Final bake out
- Shipped in JEDEC standard trays and anti-static shielded dry pack bags
- Humidity indicator cards are included
- Desiccant used in dry packs

Qualification Information

Qual for 219 PBGA Product

Qual Test	# of Pieces	Duration	Reference Standards	Temp. Range	Results
Preconditioning	All Test Sample		EIA/JESD22 Method A113		Pass
Bias Life Test	15	1,000 hrs	EIA/JESD22 Method A108	125°C	15 Pass
Temperature Cycle	15	1,000 cycles	EIA/JESD22 Method A104 Condition C	-55°C to +125°C	15 Pass
85/85 Bias	15	1,000 hrs	EIA/JESD22 Method 101		15 Pass

(Per Reliability Report)
 TBD